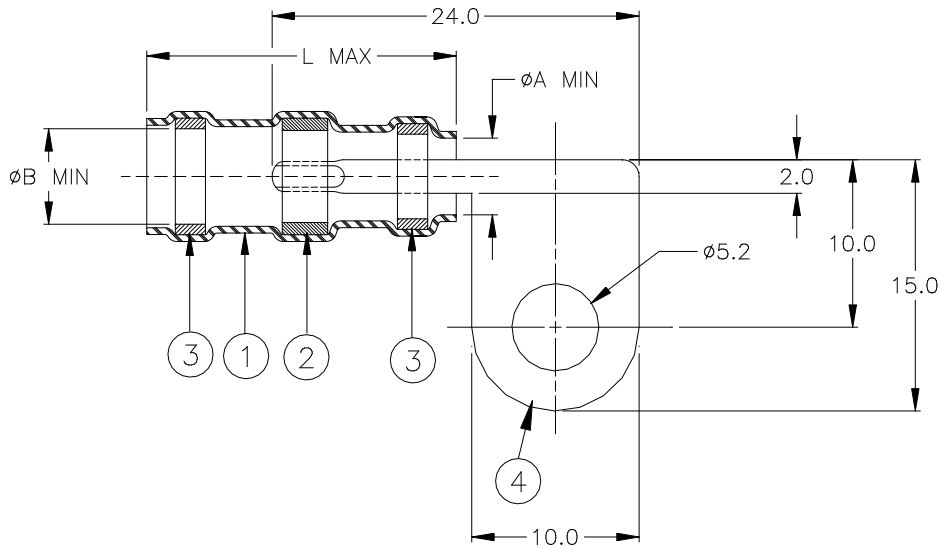


## CUSTOMER DRAWING



Product Name	Product Dimensions			Cable Dimensions		
	$\phi A$ min	$\phi B$ min	L max	$\phi E$ min	$\phi G$ max	$J \pm 0.5$ ( $J \pm 0.020$ )
B-150-05-F	4.3 (0.169)	4.8 (0.189)	18.5 (0.728)	2.0 (0.078)	4.3 (0.169)	6.5 (0.256)
B-150-07-F	6.8 (0.267)	7.3 (0.287)	21.0 (0.827)	3.3 (0.130)	6.8 (0.267)	8.0 (0.315)

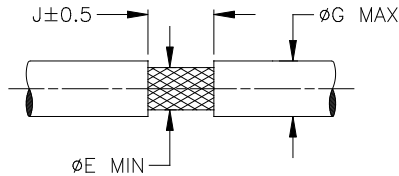
### MATERIALS

- INSULATION SLEEVE: Heat-shrinkable, transparent clear, radiation cross-linked modified polyolefin.
- SOLDER PREFORM WITH FLUX.  
SOLDER: TYPE Cd18 per ANSI-J-STD-006.  
FLUX: TYPE ROM1 per ANSI-J-STD-004.
- MELTABLE SEALING RINGS: Thermally stabilized thermoplastic.
- GROUNDING BAR: Tin plated brass alloy.


### APPLICATION

- These controlled soldering, grounding devices are designed for termination of a bare or tin plated copper shield on a cable having an insulation rated for at least +85°C.
- Temperature range: -55°C to +125°C.
- For installation procedure and application equipment, consult RPIP-688-02.

For best results, prepare the cable as shown:



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		<b>Raychem</b> THERMOFIT DEVICES		TITLE: <b>SOLDERSLEEVE WITH FLAG TERMINAL</b>	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.				DOCUMENT NO: <b>B-150-XX-F</b>	
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A  ROUGHNESS IN MICRON	TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		Revision: <b>2</b>	Issue Date: <b>April 2020</b>
PREPARED BY: M. FORONDA	DATE: 10/20/99	ECO: ECO-20-004959	SCALE: None	SIZE: A	SHEET: 1 of 1

Print Date: 21-Apr-20 If this document is printed it becomes uncontrolled. Check for the latest revision.